

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): ~~An Electronic~~ electronic device comprising:

[[ - ]] a) ~~an electronic circuit called~~ active element, comprising a semiconductor component comprising at least one of a photon or radiation detector, a photon or radiation emission device, a mechanical means, an electromechanical means, and a MEMS, said active element having a first and a second face, the first face being provided with electrical connections, arranged on one side only of said active element; ~~the circuit only;~~

[[ - ]] b) a transfer element, comprising a first face and a second face and being assembled to the second face of the active element through its first face, and having electrical connections on its second face, this transfer element being designed to be assembled on another circuit on the side of ~~this~~ its second face[[,]]; and

[[ - ]] c) at least one wire connection between the electrical connections of the first face of the active element and the second face of the transfer element.

Claim 2 (Currently Amended): ~~Device~~ The electronic device according to claim 1, the transfer element being assembled to the second face of the active element by a layer of glue, [[or]] a glue film, [[or]] a glue strip, or soldering means.

Claim 3 (Currently Amended): ~~Device~~ The electronic device according to claim 1, the wire connection being covered by a protection layer.

Claim 4 (Currently Amended): ~~Device~~ The electronic device according to claim 1, the transfer element further comprising a ceramic element.

Claim 5 (Canceled).

Claim 6 (Currently Amended): ~~Device~~ The electronic device according to claim [[5]]  
1, said active element ~~the electronic circuit~~ comprising at least one of a CMOS circuit, ~~and/or~~  
~~or~~ a CCD circuit, ~~and/or~~ an interconnections network, [[or]] and a bipolar circuit.

Claim 7 (Canceled).

Claim 8 (Currently Amended): ~~Device~~ The electronic device according to claim 1,  
further comprising:

a ~~circuit or~~ photon or radiation detector, ~~detection means~~ or a photon or radiation  
emission device, hybridized onto the first face of said active element ~~the electronic circuit~~.

Claim 9 (Currently Amended): ~~Device~~ The electronic device according to claim 1,  
~~also~~ further comprising:

a ~~photon emission circuit or means~~ mechanical or electromechanical device, or a  
MEMS, hybridized on the first face of said active element ~~the electronic circuit~~.

Claim 10 (Currently Amended): ~~Device~~ The electronic device according to claim 8 or  
9, ~~the circuits or means~~, wherein an element hybridized on the first face of said active  
element ~~the electronic circuit~~, ~~covering~~ covers the electrical connections ~~connection means~~  
located on said [[this]] first face of said active element.

Claim 11 (Currently Amended): ~~Device~~ The electronic device according to claim 1, the second face of the transfer element ~~also~~ further comprising connection balls, ~~[[or]]~~ pins, or pads.

Claim 12 (Currently Amended): ~~Electronic~~ An electronic system comprising:  
one or more electronic devices according to claim 11, each transfer element in ~~these~~ the one or more electronic devices being connected or fixed to a common substrate through connection balls, ~~[[or]]~~ pins, or pads.

Claim 13 (Currently Amended): ~~System~~ The electronic system according to claim 12, each electronic device being separated from ~~its neighbor~~ a neighboring electronic device by a distance of less than 60  $\mu\text{m}$ .

Claims 14-16 (Canceled).

Claim 17 (New): An electronic device comprising:

a) an active element, comprising a semiconductor component, said active element having a first and a second face, the first face being provided with electrical connections, arranged on only one side of said active element;

b) a transfer element, comprising a first face and a second face and being assembled to the second face of the active element through its first face, and having electrical connections on its second face, the transfer element being designed to be assembled on another circuit on the side of its second face;

c) at least one of:

a photon or radiation detector,

a photon or radiation emission device,  
a mechanical or electromechanical device, and  
a MEMS,  
being hybridized onto the first face of said active element; and  
d) at least one wire connection between the electrical connections of the first face of  
the active element and the second face of the transfer element.

Claim 18 (New): The electronic device according to claim 17, the transfer element  
being assembled to the second face of the active element by a layer of glue, a glue film, a  
glue strip, or soldering means.

Claim 19 (New): The electronic device according to claim 17, said wire connection  
being covered by a protection layer.

Claim 20 (New): The electronic device according to claim 17, the transfer element  
further comprising a ceramic element.

Claim 21 (New): The electronic device according to claim 17, said active element  
comprising at least one of a CMOS circuit, a CCD circuit, an interconnections network, and a  
bipolar circuit.

Claim 22 (New): The electronic device according to claim 17, said active element  
further comprising at least one of a photon or radiation detector, a photon or radiation  
emission device, a mechanical means, a electromechanical means, and a MEMS.

Claim 23 (New): The electronic device according to claim 17, said at least one of a photon or radiation detector, a photon or radiation emission device, a mechanical or electromechanical device, and a MEMS, hybridized on said first face of said active element, covering the electrical connections located on said first face.

Claim 24 (New): The electronic device according to claim 17, said second face of the transfer element further comprising connection balls, pins, or pads.

Claim 25 (New): An electronic system comprising:  
one or more electronic devices according to claim 17, each transfer element in the one or more electronic devices being connected or fixed to a common substrate through connection balls, pins, or pads.

Claim 26 (New): The electronic system according to claim 17, each electronic device being separated from a neighboring electronic device by a distance of less than 60  $\mu\text{m}$ .

Claim 27 (New): An electronic device comprising:  
a) an active element, comprising a semiconductor component, said active element having a first and a second face, the first face being provided with electrical connections, arranged on only one side of said active element;  
b) a transfer element, comprising a first face and a second face and being assembled to the second face of the active element through its first face, and having electrical connections on its second face, the transfer element being designed to be assembled on another circuit on the side of its second face;  
c) at least one of:

a photon or radiation detector,  
a photon or radiation emission device,  
a mechanical or electromechanical device, and  
a MEMS,

being hybridized onto the first face of said active element and covering at least part of said electrical connections of said first face of said active element; and

d) at least one wire connection between the electrical connections of said first face of said active element and said second face of said transfer element.